

## **PNP Silicon Digital Transistor**

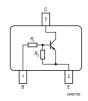
- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor (R1 = 47 k $\Omega$  , R2 = 47 k $\Omega$  )
- BCR198S: Two internally isolated transistors with good matching in one multichip package
- BCR198S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

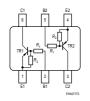




# **BCR198 BCR198W**

## **BCR198S**





Туре	Marking	Pin Configuration				Package		
BCR198	WRs	1=B	2=E	3=C	-	-	-	SOT23
BCR198S	WRs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR198W	WRs	1=B	2=E	3=C	-	-	-	SOT323



**Maximum Ratings** 

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	50	V
Collector-base voltage	$V_{CBO}$	50	
Input forward voltage	V <sub>i(fwd)</sub>	80	
Input reverse voltage	V <sub>i(rev)</sub>	10	
Collector current	I <sub>C</sub>	100	mA
Total power dissipation-	P <sub>tot</sub>		mW
BCR198, <i>T</i> <sub>S</sub> ≤ 102°C		200	
BCR198S, <i>T</i> <sub>S</sub> ≤ 115°C		250	
BCR198W, <i>T</i> <sub>S</sub> ≤ 124°C		250	
Junction temperature	$T_{j}$	150	°C
Storage temperature	T <sub>stg</sub>	-65 150	

## **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	R <sub>thJS</sub>		K/W
BCR198		≤ <b>240</b>	
BCR198S		≤ 140	
BCR198W		≤ 105	

 $<sup>^{1}</sup>$ For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation)



**Electrical Characteristics** at  $T_A = 25$ °C, unless otherwise specified **Symbol Values** Unit **Parameter** min. typ. max. **DC Characteristics**  $V_{(BR)CEO}$ ٧ 50 Collector-emitter breakdown voltage  $I_{\rm C}$  = 100  $\mu$ A,  $I_{\rm B}$  = 0 Collector-base breakdown voltage  $V_{(BR)CBO}$ 50  $I_{\rm C} = 10 \; \mu {\rm A}, \; I_{\rm E} = 0$ Collector-base cutoff current 100 nΑ  $I_{CBO}$ - $V_{\rm CB} = 40 \text{ V}, I_{\rm E} = 0$ 164 μΑ Emitter-base cutoff current *I*<sub>EBO</sub>  $V_{\rm EB}$  = 10 V,  $I_{\rm C}$  = 0 DC current gain<sup>1)</sup> 70  $h_{\mathsf{FE}}$  $I_{\rm C}$  = 5 mA,  $V_{\rm CE}$  = 5 V Collector-emitter saturation voltage<sup>1)</sup> ٧ V<sub>CEsat</sub> 0.3  $I_{\rm C}$  = 10 mA,  $I_{\rm B}$  = 0.5 mA Input off voltage  $V_{i(off)}$ 8.0 1.5  $I_{\rm C}$  = 100  $\mu$ A,  $V_{\rm CE}$  = 5 V  $V_{i(on)}$ Input on voltage 1 3  $I_{\rm C}$  = 2 mA,  $V_{\rm CE}$  = 0.3 V  $R_1$ Input resistor 32 47 62  $\mathsf{k}\Omega$  $R_1/R_2$ 0.9 1 1.1 Resistor ratio **AC Characteristics**  $f_{\mathsf{T}}$ MHz Transition frequency 190  $I_{\rm C}$  = 10 mA,  $V_{\rm CE}$  = 5 V, f = 100 MHz рF Collector-base capacitance 3  $C_{cb}$ 

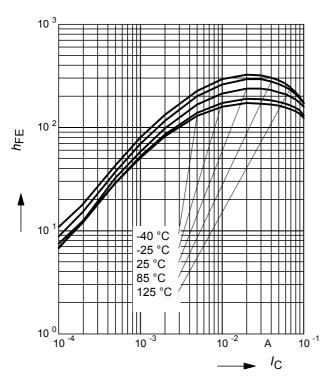
 $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$ 

<sup>&</sup>lt;sup>1</sup>Pulse test: t < 300µs; D < 2%



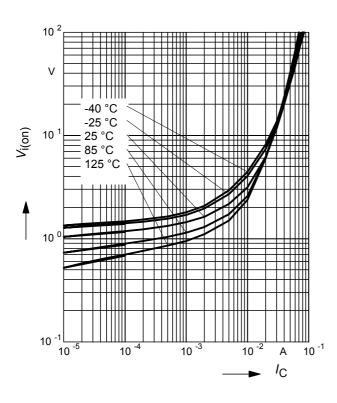
# **DC** current gain $h_{FE} = f(I_C)$

 $V_{CE}$  = 5 V (common emitter configuration)



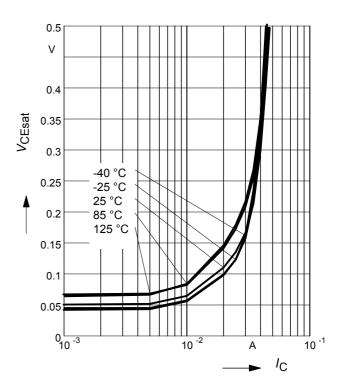
# Input on Voltage $Vi_{(On)} = f(I_C)$

 $V_{CE}$  = 0.3V (common emitter configuration)



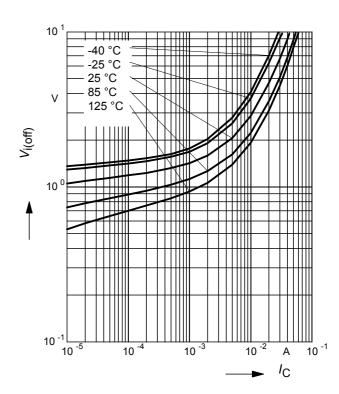
## **Collector-emitter saturation voltage**

 $V_{\text{CEsat}} = f(I_{\text{C}}), h_{\text{FE}} = 20$ 



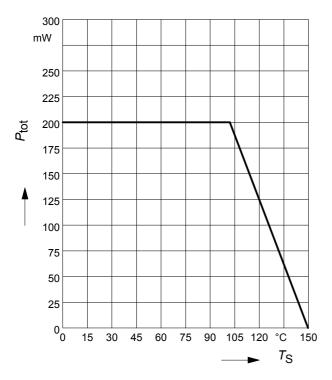
# Input off voltage $V_{i(Off)} = f(I_C)$

 $V_{CE}$  = 5V (common emitter configuration)

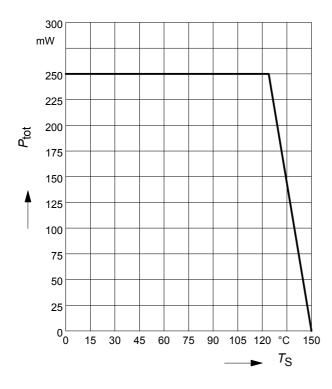




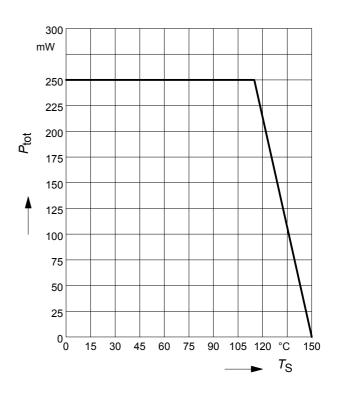
Total power dissipation  $P_{tot} = f(T_S)$  BCR198



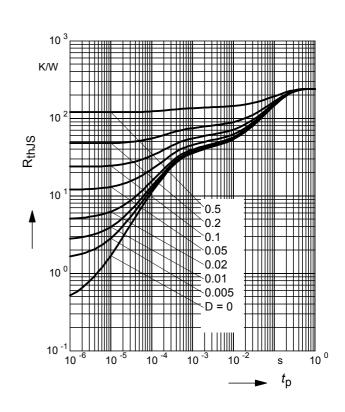
Total power dissipation  $P_{tot} = f(T_S)$ BCR198W



**Total power dissipation**  $P_{tot} = f(T_S)$  BCR198S



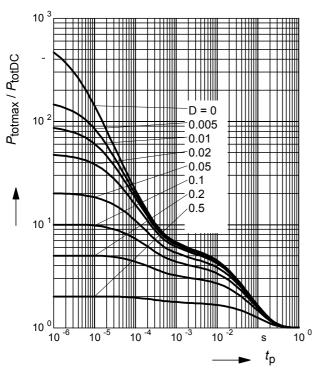
**Permissible Pulse Load**  $R_{thJS} = f(t_p)$  BCR198





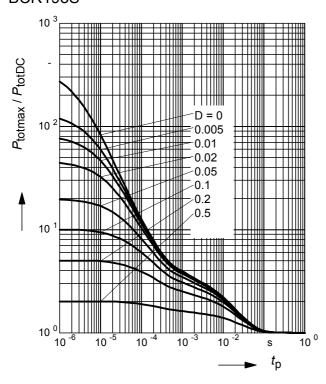
## **Permissible Pulse Load**

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR198

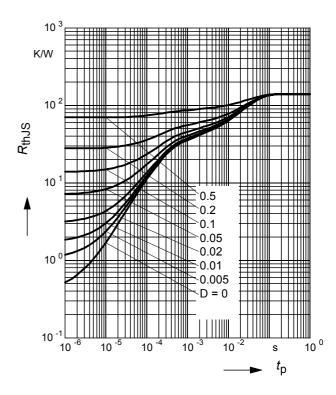


## **Permissible Pulse Load**

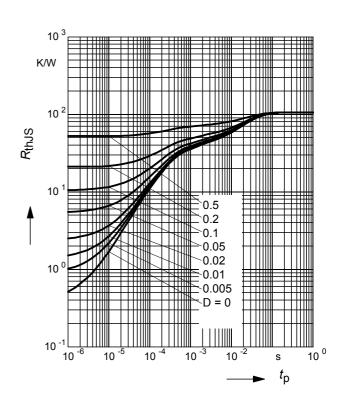
 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR198S



# **Permissible Puls Load** $R_{thJS} = f(t_p)$ BCR198S



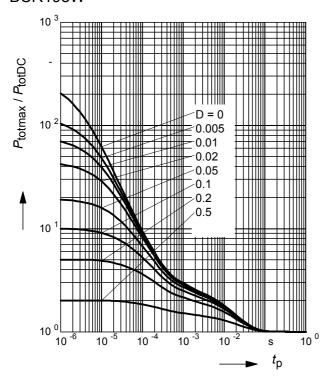
**Permissible Puls Load**  $R_{thJS} = f(t_p)$  BCR198W





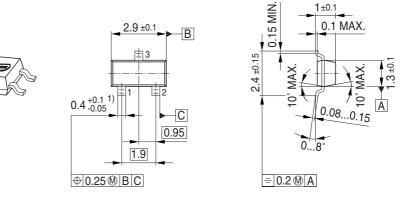
# **Permissible Pulse Load**

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR198W



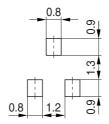


# Package Outline

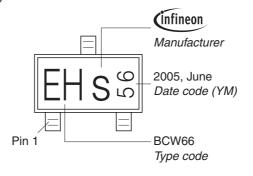


1) Lead width can be 0.6 max. in dambar area

## Foot Print

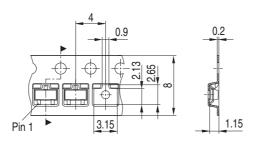


# Marking Layout (Example)



# Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

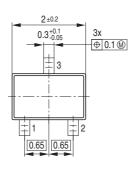


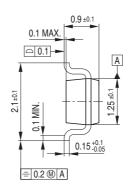
8



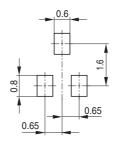
# Package Outline



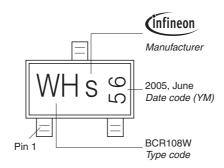




## Foot Print

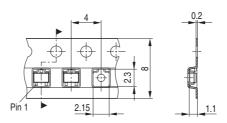


# Marking Layout (Example)



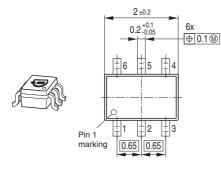
# Standard Packing

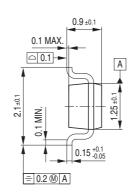
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



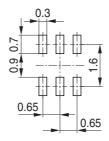


## Package Outline



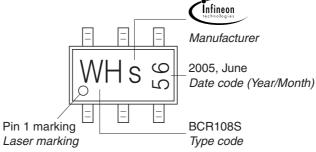


### Foot Print



# Marking Layout (Example)

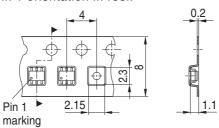
Small variations in positioning of Date code, Type code and Manufacture are possible.



# Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



10



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